

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客户: _____

PRODUCT 产品: _____ SAW RESONATOR _____

MODEL NO 型号: _____ HDR916M-S5 _____

PREPARED 编制: _____ CHECKED 审核: _____

APPROVED 批准: _____ DATE 日期: _____ 2009-1-13 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. SCOPE

This specification shall cover the characteristics of 1-port SAW resonator with 916.0M used for remote-control security.

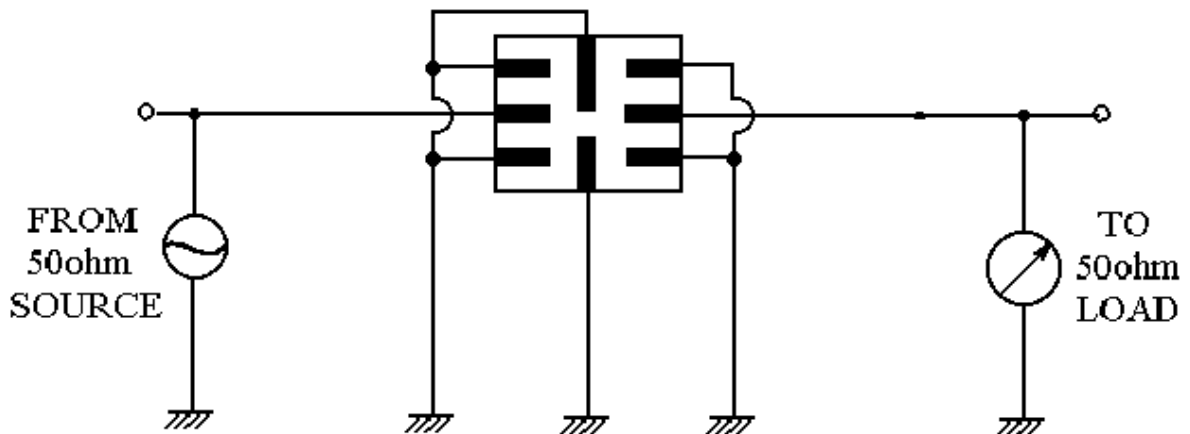
2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-20°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

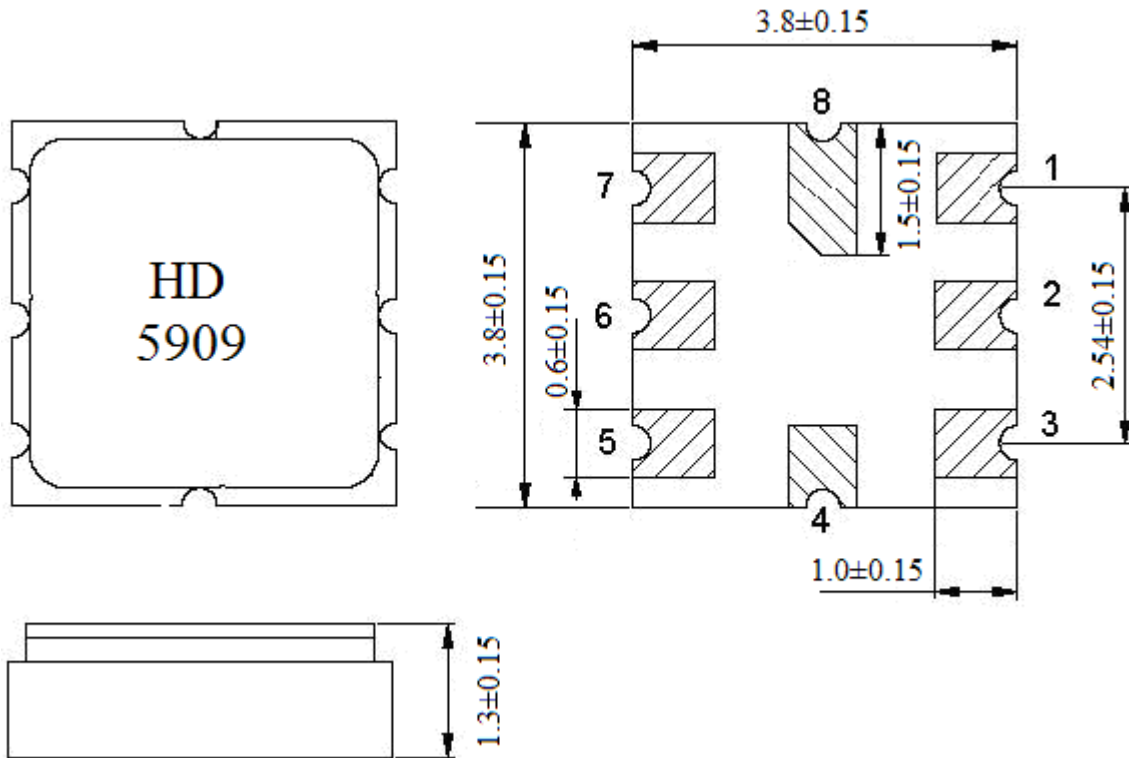
Electronic Characteristics

Item	Unites	Minimum	Typical	Maximum
Center Frequency	MHz	915.750	916.000	916.250
Insertion Loss	dB		1.5	3.5
Quality Factor Unload Q		8000	12800	
50 Ω Loaded Q		1000	2000	
Temperature Stability	Turnover Temperature	°C	39	
	Turnover Frequency	KHz	$f_0 \pm 2.7$	
	Freq.temp.Coefficient	ppm/°C ²	0.037	
Frequency Aging	ppm/yr		< ±10	
DC. Insulation Resistance	M Ω	1.0		
RF Equivalent RLC Model	Motional Resistance R1	Ω	21.76	26
	Motional Inductance L1	μ H	18.805	
	Motional Capacitance C1	fF	1.6048	
Pin 1 to Pin 2 Staic Capacitance	pF	2.7	3.1	3.5
Transducer Static Capacitance	pF		2.3	

3. TEST CIRCUIT



4. DIMENSION



5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+25^{\circ}\text{C}$ for 5 Minutes and a higher temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in table 1.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in table 1.

5-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in table 1.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the resonator shall fulfill the specifications in table 1.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The resonator shall fulfill the specifications in table 1.

5-6 Gross Leak Test

Submerge the device to absolute alcohol for at least 1 minute at +70 to +75°C. No bubbles should be seen. Measure the leak rate. Failure is defined if the leak rate exceeds 1×10^{-5} atm cc/sec Helium. Refer to MIL – STD - 202F , Method 112 for test details.

5-7 Fine Leak Test

Failure is defined if the leak rate exceeds 1×10^{-5} atm cc/sec Helium. Refer to MIL – STD - 202F , Method 112 for test details.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

7. Packing

7.1 Dimensions

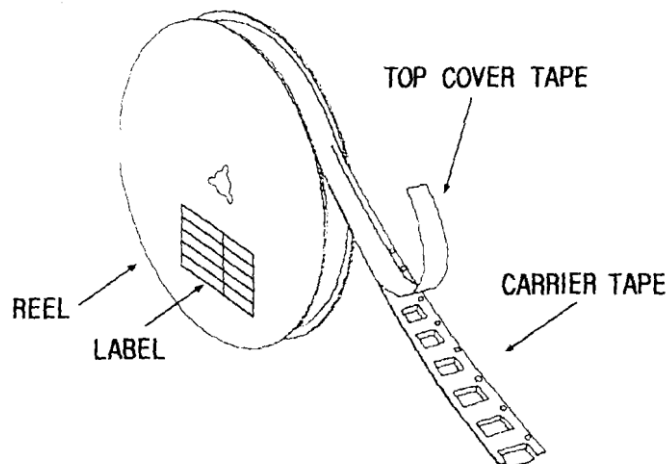
- (1) Carrier Tape: Figure 1
- (2) Reel: Figure 2
- (3) The product shall be packed properly not to be damaged during transportation and storage.

7.2 Reeling Quantity

1000 pcs/reel	7"
3000 pcs/reel	13"

7.3 Taping Structure

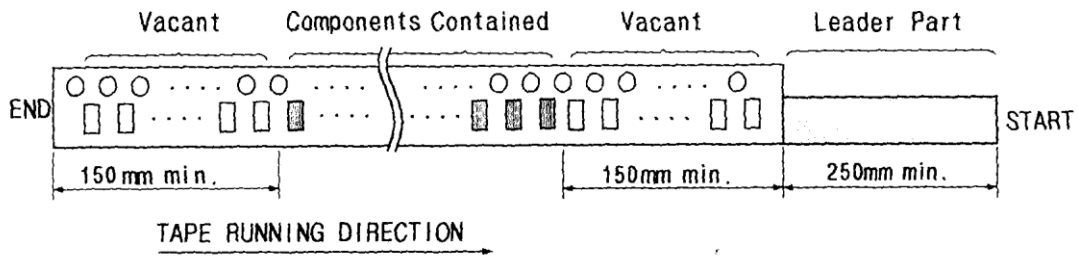
- (1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.

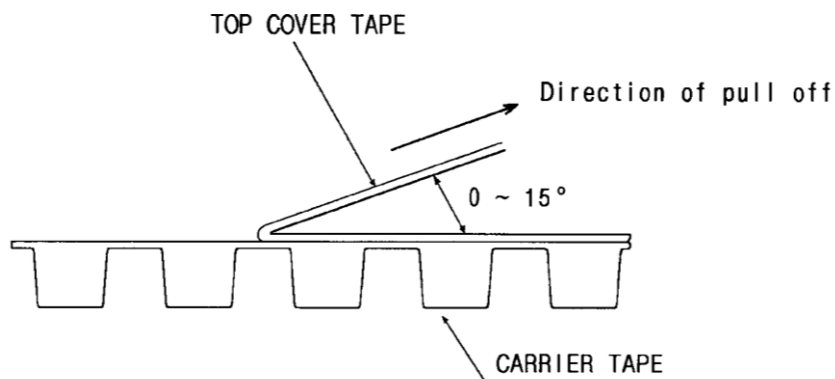


8. TAPE SPECIFICATIONS

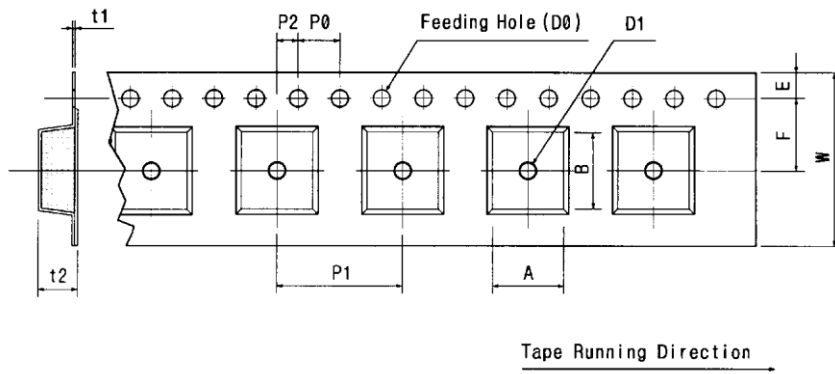
8.1 Tensile Strength of Carrier Tape: 4.4N/mm width

8.2 Top Cover Tape Adhesion (See the below figure)

- (1) pull off angle: 0~15°
- (2) speed: 300mm/min.
- (3) force: 20~70g



[Figure 1] Carrier Tape Dimensions

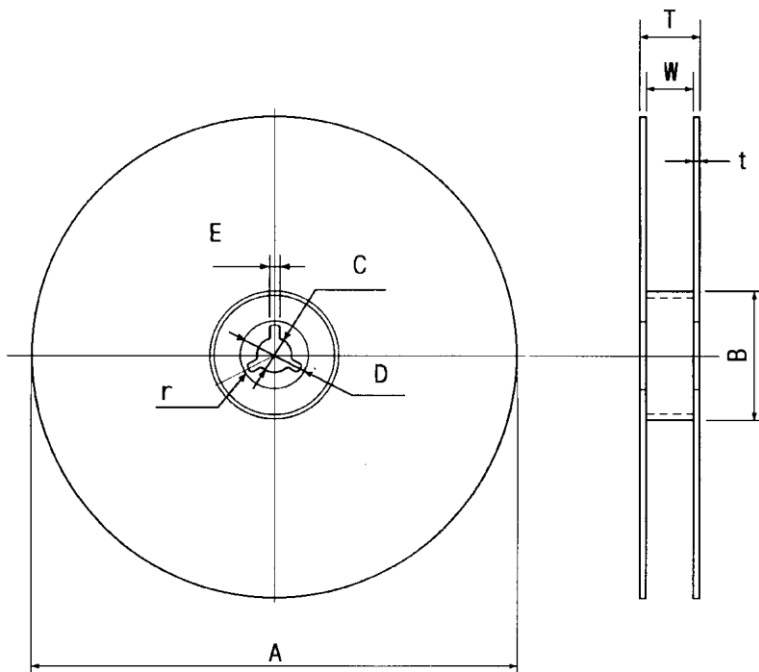


[Unit:mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.00	5.50	1.75	4.00	8.00	2.00	Ø1.50	Ø1.0	0.25	1.65	4.04	4.10
±0.30	±0.10	±0.10	±0.10	±0.10	±0.10		±0.25	±0.05	±0.10	±0.10	±0.10

[Figure 2]

[Unit:mm]



A	B	C	D	E	W	t	r
Ø330	Ø100	Ø13	Ø21	2	13	3	1.0
±1.0	±0.5	±0.5	±0.8	±0.5	±0.3	max.	max.